

RELIABILITY MONITOR

PROCESS: 0.6 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21352	A4	DEC '00	26355	0044	ATP (Anam, PI)	DK031452AB	LQFP	48	231	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21352	A4	DEC '00	26356	0044	ATP (Anam, PI)	DK031452AB	LQFP	336	77	0

TOTALS FOR: 0.6 μ m Double Poly, Double Metal (Ti/T) FAIL RATE (Fits): 194 DEVICE HRS: 4.72E+06 0

RELIABILITY MONITOR

PROCESS: 0.6 μ m Double Poly, Single Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2502	C3	JUN '00	25568	0011	Carsem S	DM941230AG	SOIC	48	231	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2502	C3	JUN '00	25569	0011	Carsem S	DM941230AG	SOIC	336	77	0
DS2502	C3	JUN '00	25569	0011	Carsem S	DM941230AG	SOIC	1000	77	0

TOTALS FOR: 0.6 μ m Double Poly, Single Metal (Ti/Ti) FAIL RATE (Fits): 81 DEVICE HRS: 1.13E+07 0

RELIABILITY MONITOR

PROCESS: 0.6 μ m Single Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS80CH11	A4	DEC '00	26398	0033	ATK (Anam, K)	DN022359AAA	LQFP	48	235	0

TOTALS FOR: 0.6 μ m Single Poly, Double Metal (Ti/Ti) FAIL RATE (Fits): 635 DEVICE HRS: 1.44E+06 0

RELIABILITY MONITOR

PROCESS: 0.6 µm Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21Q43	A3-A	DEC '00	26369	0034	ATK (Anam, K)	DN027568AAC	LQFP	48	234	0
DS21Q43	A3-A	JUN '00	25504	0014	ATK (Anam, K)	DN004571AAB	LQFP	48	224	0
DS21Q43	A3-A	SEP '00	25950	0031	Stats	DC022318AAD	LQFP	48	231	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21Q43	A3-A	JUN '00	25505	0014	ATK (Anam, K)	DN004571AAB	LQFP	336	77	0
DS21Q43	A3-A	JUN '00	25505	0014	ATK (Anam, K)	DN004571AAB	LQFP	1000	75	0
DS21Q43	A3-A	SEP '00	25951	0031	Stats	DC022318AAD	LQFP	336	77	0
DS21Q43	A3-A	SEP '00	25951	0031	Stats	DC022318AAD	LQFP	1000	75	0

TOTALS FOR: 0.6 µm Single Poly, Single Metal FAIL RATE (Fits): 40 DEVICE HRS: 2.32E+07 0

RELIABILITY MONITOR

PROCESS: 0.6 μ m Single Poly, Single Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2118M	B1	SEP '00	25943	0033	ATK (Anam, K)	DN020718AAD	SSOP	48	231	0
DS2118M	B1	DEC '00	26362	0047	ATK (Anam, K)	DN033148ACE	SSOP	48	233	7
DS2401	C2	DEC '00	26337	0035	Fastech	DM014457AD	TO92	48	234	0
DS5002	C5	OCT '00	26059	0033	ATK (Anam, K)	DN022328AAJ	MQFP	48	195	0
DS5002	C5	JUL '00	25826	0027	ATK (Anam, K)	DN012259AAL	MQFP	48	198	0
DS80C320	C5	JAN '01	26455	0049	CPS (ChipPac, China)	DH031585BAA	PDIP	48	234	0
DS80C320	C5	OCT '00	26064	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	48	234	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2118M	B1	DEC '00	26363	0047	ATK (Anam, K)	DN033148ACE	SSOP	336	77	0
DS2118M	B1	SEP '00	25944	0033	ATK (Anam, K)	DN020718AAD	SSOP	336	77	0
DS2118M	B1	DEC '00	26363	0047	ATK (Anam, K)	DN033148ACE	SSOP	1000	77	0
DS2118M	B1	SEP '00	25944	0033	ATK (Anam, K)	DN020718AAD	SSOP	1000	76	0
DS2401	C2	DEC '00	26338	0035	Fastech	DM014457AD	TO92	336	77	0
DS2401	C2	DEC '00	26338	0035	Fastech	DM014457AD	TO92	1000	77	0
DS5002	C5	JUL '00	25827	0027	ATK (Anam, K)	DN012259AAL	MQFP	336	77	0
DS5002	C5	OCT '00	26060	0033	ATK (Anam, K)	DN022328AAJ	MQFP	336	77	0
DS5002	C5	JUL '00	25827	0027	ATK (Anam, K)	DN012259AAL	MQFP	1000	76	0

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DS5002	C5	OCT '00	26060	0033	ATK (Anam, K)	DN022328AAJ	MQFP	1000	77	0
DS80C320	C5	JAN '01	26456	0049	CPS (ChipPac, China)	DH031585BAA	PDIP	336	77	0
DS80C320	C5	OCT '00	26065	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	336	77	0
DS80C320	C5	OCT '00	26065	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	1000	77	0

TOTALS FOR: 0.6 μ m Single Poly, Single Metal (Ti/Ti) FAIL RATE (Fits): 84 DEVICE HRS: 9.97E+07 7

RELIABILITY MONITOR

PROCESS: 0.8 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	SEP '00	25958	0034	ATP (Anam, PI)	DK022283AAA	LQFP	48	191	0
DS2154	A2	DEC '00	26377	0036	Stats	DC022275AAB	LQFP	48	231	2

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	SEP '00	25959	0034	ATP (Anam, PI)	DK022283AAA	LQFP	336	60	0
DS2154	A2	SEP '00	25959	0034	ATP (Anam, PI)	DK022283AAA	LQFP	1000	60	0
DS2154	A2	DEC '00	26378	0036	Stats	DC022275AAB	LQFP	336	77	0

TOTALS FOR: 0.8 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals) FAIL RATE (Fits): 86 DEVICE HRS: 3.62E+07 2

RELIABILITY MONITOR

PROCESS: 0.8 μ m Double Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS87C520	A15	NOV '00	26200	0042	OSEP	DE029195AAB	PLCC	48	231	1
DS87C520	A15	AUG '00	25866	0027	OSEP	DE013425AAD	PLCC	48	234	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS87C520	A15	NOV '00	26201	0042	OSEP	DE029195AAB	PLCC	336	77	0
DS87C520	A15	AUG '00	25867	0027	OSEP	DE013425AAD	PLCC	336	77	0
DS87C520	A15	NOV '00	26201	0042	OSEP	DE029195AAB	PLCC	1000	77	0
DS87C520	A15	AUG '00	25867	0027	OSEP	DE013425AAD	PLCC	1000	77	0

TOTALS FOR: 0.8 μ m Double Poly, Single Metal FAIL RATE (Fits): 33 DEVICE HRS: 6.16E+07 1

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Double Metal

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1803	A2	NOV '99	24739	9923	ATP (Anam, PI)	DK913631AAA	SOIC	1000	77	0
DS1803	A2	FEB '00	25192	0007	OSEP	DE946274AAA	SOIC	336	75	0
DS1803	A2	MAY '00	25439	0013	OSEP	DE951193AAF	SOIC	336	76	0

TOTALS FOR: 0.8 μ m Single Poly, Double Metal FAIL RATE (Fits): 28 DEVICE HRS: 3.28E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 µm Single Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1302	A3	DEC '00	26332	0032	CPS (ChipPac, China)	DH028629AB	PDIP	48	234	0
DS1302	A3	AUG '00	25931	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	48	234	0
DS1803	A2	NOV '99	24738	9923	ATP (Anam, PI)	DK913631AAA	SOIC	48	224	0
DS1803	A2	FEB '00	25191	0007	OSEP	DE946274AAA	SOIC	48	226	0
DS1803	A2	MAY '00	25438	0013	OSEP	DE951193AAF	SOIC	48	227	0
DS1803	A2	AUG '00	25925	0034	OSEP	DE023435AAB	SOIC	48	221	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1302	A3	AUG '00	25932	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	336	77	0
DS1302	A3	DEC '00	26333	0032	CPS (ChipPac, China)	DH028629AB	PDIP	336	77	0
DS1302	A3	AUG '00	25932	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	1000	76	0
DS1803	A2	NOV '99	24739	9923	ATP (Anam, PI)	DK913631AAA	SOIC	336	77	0
DS1803	A2	AUG '00	25926	0034	OSEP	DE023435AAB	SOIC	336	77	0
DS1803	A2	FEB '00	25192	0007	OSEP	DE946274AAA	SOIC	1000	62	0
DS1803	A2	MAY '00	25439	0013	OSEP	DE951193AAF	SOIC	1000	65	0

TOTALS FOR: 0.8 µm Single Poly, Double Metal (Ti/TiN) FAIL RATE (Fits): 12 DEVICE HRS: 7.65E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1232	C2-L	JAN '01	26435	0051	ATP (Anam, PI)	DK038265AAC	SOIC	48	233	0
DS1232	C2-L	OCT '00	26089	0039	OSEP	DE028679ADB	SOIC	48	232	0
DS1621	A7	MAR '00	25220	9950	OSEP	DE940040AAC	SOIC	48	237	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1232	C2-L	OCT '00	26090	0039	OSEP	DE028679ADB	SOIC	336	77	0
DS1232	C2-L	OCT '00	26090	0039	OSEP	DE028679ADB	SOIC	1000	77	0
DS1621	A7	MAR '00	25221	9950	OSEP	DE940040AAC	SOIC	336	77	0
DS1621	A7	MAR '00	25221	9950	OSEP	DE940040AAC	SOIC	1000	77	0

TOTALS FOR: 0.8 μ m Single Poly, Single Metal FAIL RATE (Fits): 14 DEVICE HRS: 6.56E+07 0

RELIABILITY MONITOR

PROCESS: 1.2 µm Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1000	E3	OCT '00	26046	0033	OSEP	DE009456ACE	SOIC	48	234	0
DS1233	A5	JUL '00	25800	0025	Carsem	DM009468AA	SOT223	48	221	0
DS1233	A5	OCT '00	26126	0038	Fastech	DA017172ABA	SOT223	48	225	0
DS1233	A5	JAN '01	26443	0049	Fastech	DA033011ABA	SOT223	48	225	0
DS1267	A2	FEB '00	25175	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	48	226	0
DS1267	A1	AUG '00	25834	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	48	224	0
DS1267	A1	FEB '01	26571	0102	Carsem S	DM039441AB	TSSOP	48	234	0
DS1869	A3	JUN '00	25543	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	48	236	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1000	E3	OCT '00	26047	0033	OSEP	DE009456ACE	SOIC	336	77	0
DS1000	E3	OCT '00	26047	0033	OSEP	DE009456ACE	SOIC	1000	76	0
DS1233	A5	JUL '00	25801	0025	Carsem	DM009468AA	SOT223	336	75	0
DS1233	A5	JUL '00	25801	0025	Carsem	DM009468AA	SOT223	1000	68	1
DS1233	A5	JAN '01	26444	0049	Fastech	DA033011ABA	SOT223	336	68	0
DS1233	A5	OCT '00	26127	0038	Fastech	DA017172ABA	SOT223	336	68	0
DS1233	A5	OCT '00	26127	0038	Fastech	DA017172ABA	SOT223	1000	68	0
DS1267	A1	AUG '00	25835	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	336	77	0

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DS1267	A2	FEB '00	25176	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	336	77	0
DS1267	A2	FEB '00	25176	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	1000	77	13
DS1267	A1	AUG '00	25835	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	1000	73	0
DS1869	A3	JUN '00	25544	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	336	76	1

TOTALS FOR: 1.2 μ m Single Poly, Single Metal FAIL RATE (Fits): 126 DEVICE HRS: 1.33E+08 15

RELIABILITY MONITOR

PROCESS: 2.0 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2175	D1	OCT '00	26108	0042	ATP (Anam, PI)	DK031506AAC	SOIC	48	234	0
DS2181A	A2	JUL '00	25818	0016	OSEP	DE004552ABD	PLCC	48	237	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2175	D1	OCT '00	26109	0042	ATP (Anam, PI)	DK031506AAC	SOIC	336	77	0
DS2181A	A2	JUL '00	25819	0016	OSEP	DE004552ABD	PLCC	336	77	0

TOTALS FOR: 2.0 μ m Single Poly, Single Metal FAIL RATE (Fits): 35 DEVICE HRS: 2.60E+07 0

RELIABILITY MONITOR

PROCESS: 5.0 µm Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2108	B7	FEB '01	26579	0051	ATK (Anam, K)	DN041061AAE	SOIC	48	234	0
DS2108	B7	AUG '00	25857	0029	ATP (Anam, PI)	DK016058AA	SOIC	48	231	0
DS2108	B7	MAY '00	25525	0019	ATP (Anam, PI)	DK007198AAF	SOIC	48	231	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2108	B7	MAY '00	25526	0019	ATP (Anam, PI)	DK007198AAF	SOIC	336	77	0
DS2108	B7	AUG '00	25858	0029	ATP (Anam, PI)	DK016058AA	SOIC	336	77	0
DS2108	B7	MAY '00	25526	0019	ATP (Anam, PI)	DK007198AAF	SOIC	1000	77	0
DS2108	B7	AUG '00	25858	0029	ATP (Anam, PI)	DK016058AA	SOIC	1000	76	0

TOTALS FOR: 5.0 µm Single Poly, Single Metal FAIL RATE (Fits): 39 DEVICE HRS: 2.38E+07 0